

Title (en)  
DEVICE AND FORMING METHOD OF DEVICE

Title (de)  
VORRICHTUNG UND HERSTELLUNGSVERFAHREN DER VORRICHTUNG

Title (fr)  
DISPOSITIF ET PROCÉDÉ DE FORMATION DE DISPOSITIF

Publication  
**EP 4013197 A1 20220615 (EN)**

Application  
**EP 21204222 A 20211022**

Priority  
JP 2020205499 A 20201211

Abstract (en)  
A device comprises a first sealing member basically comprising a first film formed of a film, a second sealing member, a first circuit member comprising a first contact point and a second circuit member comprising a second contact point. The device is formed with a closed space which is enclosed by the first sealing member and the second sealing member and is shut off from an outer space outside the device. The first circuit member and the second circuit member are shut in the closed space. At least one of the first sealing member and the second sealing member is provided with an uneven portion. The uneven portion is in contact with at least one of the first circuit member and the second circuit member and covers a predetermined region which corresponds to at least one of the first contact point and the second contact point.

IPC 8 full level  
**H05K 5/00** (2006.01); **A61B 5/024** (2006.01); **B32B 7/04** (2019.01)

CPC (source: CN EP KR US)  
**H01L 23/293** (2013.01 - KR); **H01L 23/3107** (2013.01 - KR); **H01L 25/16** (2013.01 - KR); **H05K 1/11** (2013.01 - US); **H05K 3/28** (2013.01 - KR); **H05K 5/0086** (2013.01 - CN EP); **H05K 5/0095** (2013.01 - EP); **H05K 5/065** (2013.01 - CN); **H05K 5/069** (2013.01 - US); **H05K 7/005** (2013.01 - CN); **H05K 13/00** (2013.01 - CN); **A61B 5/024** (2013.01 - EP); **H01L 2224/16245** (2013.01 - EP); **H01L 2924/181** (2013.01 - EP); **H01L 2924/18161** (2013.01 - EP)

C-Set (source: EP)  
**H01L 2924/181** + **H01L 2924/00012**

Citation (applicant)  
JP 2001332654 A 20011130 - MATSUSHITA ELECTRIC IND CO LTD

Citation (search report)  
• [XAI] US 4933042 A 19900612 - EICHELBERGER CHARLES W [US], et al  
• [XI] US 5605547 A 19970225 - LAKE RICKIE C [US]  
• [A] US 7498099 B2 20090303 - OTOHATA MAKIHIRO [JP], et al  
• [A] CN 201545294 U 20100811 - DELONG XING  
• [A] US 3910008 A 19751007 - JOHNSON H WILLIAM

Designated contracting state (EPC)  
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)  
BA ME

DOCDB simple family (publication)  
**EP 4013197 A1 20220615**; **EP 4013197 B1 20230712**; CN 114630537 A 20220614; CN 114630537 B 20240430; JP 2022092661 A 20220623; KR 102606997 B1 20231129; KR 20220083566 A 20220620; TW 202224120 A 20220616; TW I781782 B 20221021; US 11792949 B2 20231017; US 2022192043 A1 20220616

DOCDB simple family (application)  
**EP 21204222 A 20211022**; CN 202111212678 A 20211018; JP 2020205499 A 20201211; KR 20210140090 A 20211020; TW 110136992 A 20211005; US 202117499002 A 20211012